

# Material Composition Specification

## DO-35 Case



Device average mass . . . . . 136 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.018%	0.024	Si	7440-21-3	0.013%	0.018	132
				Ag	7440-22-4	0.004%	0.006	44
leadframe	metal alloy	72.618%	98.76	Fe	7439-89-6	48.787%	66.35	487,868
				Cu	7440-50-8	21.162%	28.78	211,618
				Ni	7440-02-0	2.669%	3.63	26,691
encapsulation	glass	25.103%	34.14	SiO <sub>2</sub>	14808-60-7	10.044%	13.66	100,441
				PbO	1317-36-8	15.059%	20.48	150,588
plating*	tin/lead process	2.235%	3.04	Sn	7440-31-5	1.788%	2.432	17,882
				Pb	7439-92-1	0.447%	0.608	4,471
	100% tin process	2.235%	3.04	Sn	7440-31-5	2.235%	3.04	22,353
ink	N/A	0.026%	0.036	tributyl-phosphate	126-73-8	0.016%	0.022	162
				carbon black	1333-96-4	0.004%	0.005	37
				phenol	108-95-2	0.001%	0.001	7
				Proprietary	--	0.006%	0.008	59

\*For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

### Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)